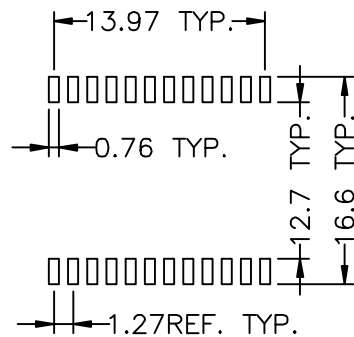
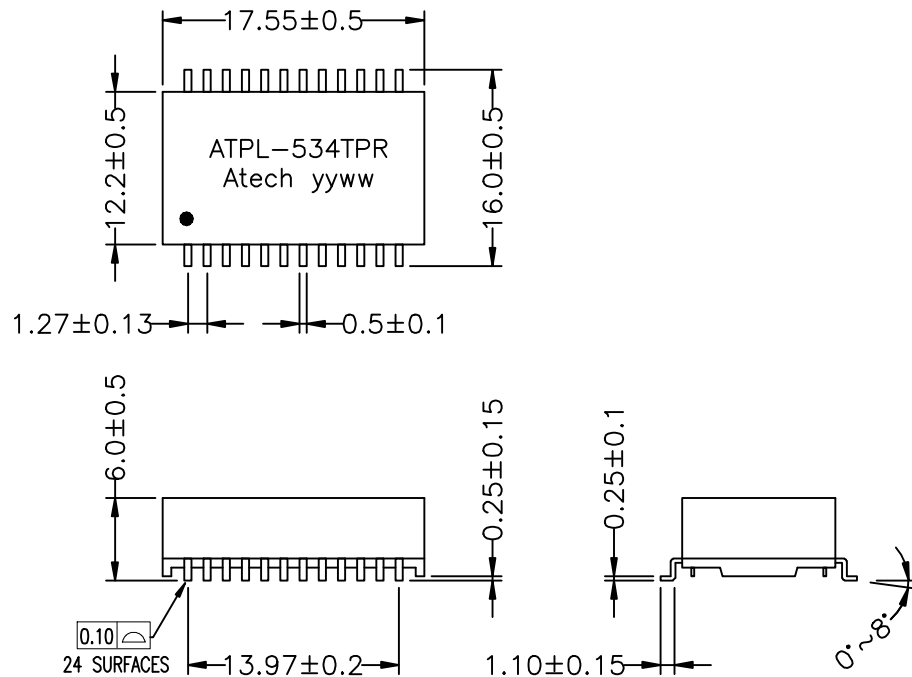
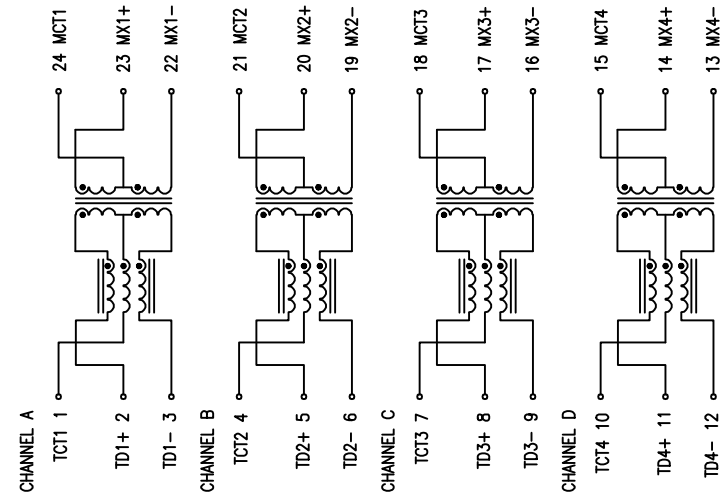




SUGGESTED PAD LAYOUT



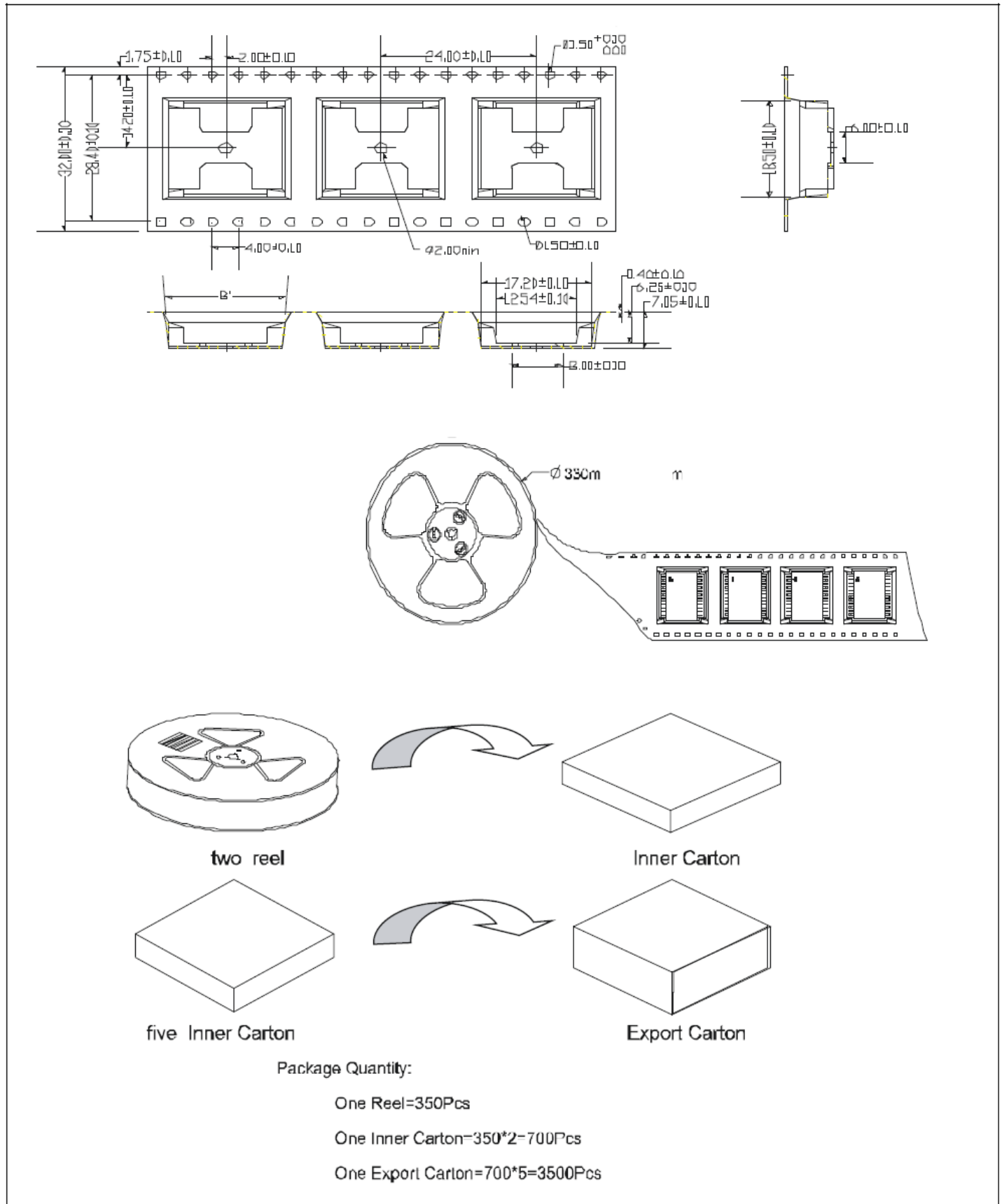
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS@25°C

1. OCL : (@100kHz, 0.1V) : 150uH MIN. @100kHz, 0.1V, 21mA DC BIAS(0°C to +70°C)
120uH MIN. @100kHz, 0.1V, 21mA DC BIAS(-40°C to +85°C)
2. LEAKAGE INDUCTANCE : (@100kHz, 0.1V) : 0.5uH MAX.
3. DCR : 1.0Ω MAX.
4. TURNS RATIO : 1CT : 1CT ±5%
5. INSERTION LOSS : (@1-100MHz) : -1.0dB MAX.
(@100-200MHz) : -2.0dB MAX.
6. RETURN LOSS : (@1≤f≤40MHz) : -16dB MIN.
(@40<f≤200MHz, where f is in MHz) : -16+10 log (f/40)dB MIN.
7. CROSS TALK : (@1-200MHz) : -30dB MIN.
8. COMMON MODE REJECTION : (@1-200MHz) : -30dB MIN.
9. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
10. PoE Support 100W : Each channel support 1A DC balance current
Full channel support 2A DC balance current
11. OPERATING TEMPERATURE : -40°C to +85°C
12. STORAGE TEMPERATURE : -40°C to +125°C

								TITLE	
								2.5G/5G POE* TRANSFORMER	
								DWG. NO.	
								ATPL-534TPR	
	RELEASE	07/31/2019	SHIRLEY	BETTY	BETTY	UNITS:	SAFETY		
						M/M			
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	SHEET 1 of 1	
REVISIONS						07/31/19	DRAW		
							SHIRLEY		

3. Package :



Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to T _p)	3°C/second max	3°C/second max
Preheat Temperature Min (T _{smin}) Temperature Min (Tsmax) Time (T _{smin} to Tsmax) (ts)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T _L) Time (t _L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T _p)	225°C	260°C
Time within 5°C of actual Peak Temperature (T _p) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max